

# AN6353 Dynex High Power IGBT Optimization Guide Application Note AN6353-1 February 2021 (LN40605)

# Introduction

Dynex's IGBT offering is optimized for several applications across voltage ratings from 750V-6500V; this application note is to aid in the selection of the appropriate optimized High Power (3300V-6500V) IGBT variant.

Refer to AN5700 for a complete explanation of Dynex's IGBT naming convention.



### AN6353

#### VCE VS ESW

The  $V_{CE}$  /  $E_{SW}$  trade-off is determined by the current gain of the bipolar part of an IGBT; high current gain devices will have Low V<sub>CE</sub> and High  $E_{SW}$ ; conversely devices with a lower current gain will have High V<sub>CE</sub> and Low  $E_{SW}$ .

Dynex's IGBT offerings will typically feature a low  $E_{SW}$ , Low  $V_{CE}$  and balanced  $E_{SW}$   $V_{CE}$  variants; which are identified with the following suffixes.

Variant	Identifier
Low E <sub>sw</sub>	DIM*F***
Low V <sub>CE</sub>	DIM*L***
Balanced (standard)	DIM*S***

Dynex Optimized Variant Identifier (E.g. DIM1500ESM33-**TF000**)

This enables the designer to select optimized chip variants, in which criteria for switching frequency and forward currents can be simultaneously evaluated. Consult with Dynex AN5700 for device naming nomenclature and our Product Guide for our complete IGBT offering. The tradeoff figures on page 3 show how the optimized variants compare to each other regarding  $V_{CE}$  and  $E_{SW}$ .

### Low Esw / F Applications

Generally speaking, Low  $E_{SW}$  / F variants; are ideal choices for applications with switching frequencies above 250Hz (6500V/4500V) - 750Hz (3300V). Typically, higher switching applications are DC/DC converters, active front

end rectifiers and inverters. While the F variants have significantly higher  $V_{CE}$  / Conduction Losses; their lower  $V_{CE}$  counterparts will suffer disproportionally higher switching losses at the same forward current and frequency. The Application Example section of this application note details the conduction vs switching losses by chip variant in a generic inverter application.

### Low V<sub>CE</sub> / L Applications

Applications with switching frequencies below 150-200Hz favour Low  $V_{CE}$  devices, with elevated switching losses that realize their low on-state losses to their best potential. Transmission/Generation tied MMCs are an ideal application for L variant IGBT modules; a generic MMC simulation is shown in the Application Example in which the benefits of the L variant shown.

### **S** Variant Applications

The S variant will deliver slightly higher  $V_{CE}$  and Esw; which can suit ZVS, interrupter/breaker and refurbishment applications.

### Trade off Comparison

The following figures show the related  $V_{CE}$  and  $E_{SW}$  obtained from Figures 4 and 5 of the datasheets:

DIM1500ESM33-T( <b>F/L/S</b> )000	3300V d <sup>2</sup>
DIM1200ASM45-T( <b>F/L/S</b> )000	4500V d <sup>2</sup>
DIM750ASM45-T( <b>F/L/S</b> )000	6500V d <sup>2</sup>

The relationship between the three optimization offerings is shown on the following page.



T Series d<sup>2</sup> 3300V / 1500A Modules

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### Application Example – 1 Ph Voltage Source Inverter



## Application Example Modular Multilevel Converter



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